

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHIYU SUN	07/27/2018
NAM SUNG KIM	07/27/2018
JOHN O. DUKOVIC	07/27/2018
RECEIVING PARTY DATA	
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Street Address:	3050 BOWERS AVENUE
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16502129
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ATTORNEY DOCKET NUMBER:	44015597US02
NAME OF SUBMITTER:	KEITH TABOADA
SIGNATURE:	/Keith Taboada/
DATE SIGNED:	07/03/2019
Total Attachments: 2	
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Atty Dkt No.: 44015597US01

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	Shiyu SUN 100 Buckingham Drive, Apt. 246 Santa Clara, California 95051	2)	Nam Sung KIM 974 E. Arques Avenue Sunnyvale, California 94085
3)	John O. DUKOVIC 1525 Walnut Drive Palo Alto, California 94303	4)	

(hereinafter referred to as Assignors), have invented a certain invention entitled:

METHODS FOR FORMING DEVICE ISOLATION FOR SEMICONDUCTOR APPLICATIONS

for which application for Letters Patent in the United States was filed on July 20, 2018, under Serial No. 62/701,234, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, conventional, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefore and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

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3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1)	7/27/2018 12:36:44 PM CDT _____ (DATE)	<div style="border: 1px dashed black; padding: 2px; display: inline-block;">DocuSigned by: <i>Shiyu Sun</i> A98638CCFAE74FB...</div> _____ Shiyu SUN
2)	7/27/2018 3:12:32 PM CDT _____ (DATE)	<div style="border: 1px dashed black; padding: 2px; display: inline-block;">DocuSigned by: <i>Nam Sung Kim</i> F6A9EBBB8A594AF...</div> _____ Nam Sung KIM
3)	7/27/2018 4:31:29 PM CDT _____ (DATE)	<div style="border: 1px dashed black; padding: 2px; display: inline-block;">DocuSigned by: <i>John O. DUKOVIC</i> 14D0AB1B717146C...</div> _____ John O. DUKOVIC